

ABSTRACT OF THE DISCLOSURE

Disclosed are a semiconductor device, a method for manufacturing the same, and a method for mounting the same. The method for manufacturing a semiconductor device includes the steps of: preparing a package film having a planar configuration whose region is divided into a device-mounting film portion having a device hole forming therein, an external-connection film portion, and a bent portion located between the device-mounting film portion and the external-connection film portion, an external electrode pad being formed on the external-connection film portion on a first surface side of the package film, an inner lead being formed in such a manner as to lead from the device hole to the external electrode pad via the bending portion; mounting a semiconductor chip on the device-mounting film portion on the first surface side by bonding the inner lead to an electrode pad of the semiconductor chip in a region where the device hole is formed; and bending the external-connection film portion at the bending portion 180° toward a second surface side of the package film and fixing the same. The method for mounting a semiconductor device on a mother board in close contact therewith includes the steps of: depositing solder balls on electrode pads of the mother board; and placing the semiconductor device on the mother board and melting the solder balls so as to electrically

connect the electrode pads of the mother board and the external electrode pads of the semiconductor device.

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A semiconductor device includes a semiconductor chip having an edge and having a surface with a plurality of electrodes. A film is mounted over the surface of the semiconductor chip, the film has first and second surfaces and has a device hole. The first surface of the film is oriented toward the surface of the semiconductor chip and so that the device hole exposes the electrodes of the semiconductor chip. Connecting conductors are disposed at the first surface of the film and extend into the device hole to the electrodes. Electrode pad holes are provided in the film, at positions between the device hole and the edge of the semiconductor chip to expose the conductors.